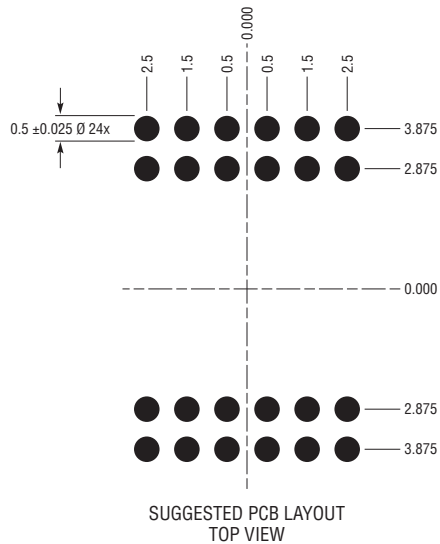
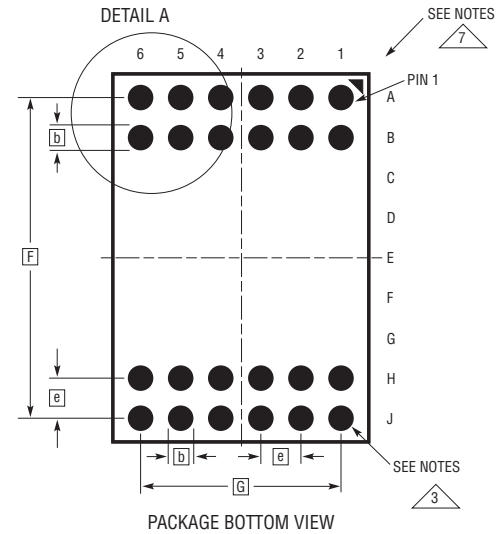
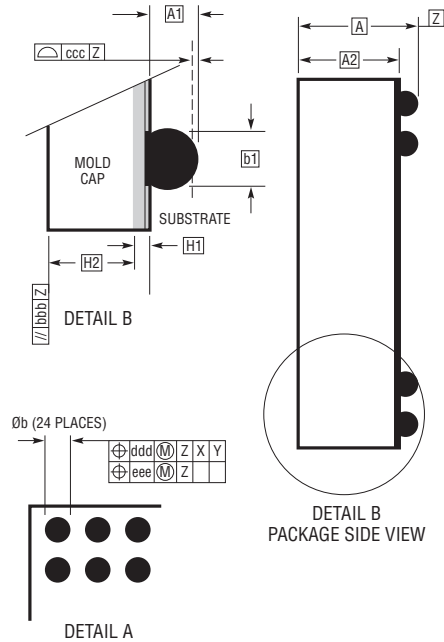
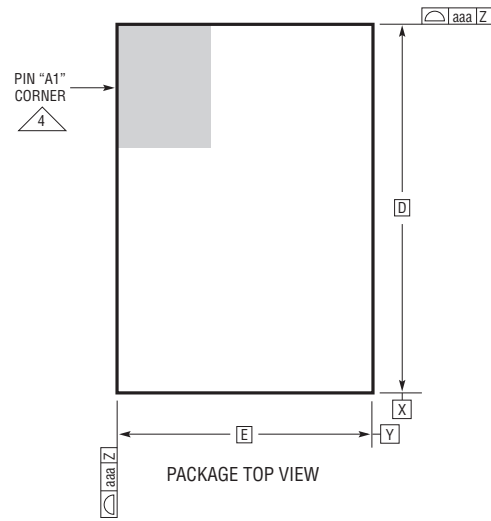


BGA Package
24-Lead (9mm × 6.25mm × 2.91mm)
 (Reference LTC DWG # 05-08-1898 Rev B)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.71	2.91	3.11	
A1	0.40	0.50	0.60	
A2	2.31	2.41	2.51	
b	0.50	0.60	0.70	
b1	0.45	0.50	0.55	
D		9.00		
E		6.25		
e		1.00		
F		7.75		
G		5.00		
H1	0.36	0.41	0.46	
H2	1.95	2.00	2.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 24				

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
 - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

